Product Change Notification: JPZA-02GYZA830

Date:

14-Sep-2026

Product Category:

Ethernet Phys, Ethernet Switches

Notification Subject:

CCB 8382 Final Notice: Qualification of ATP7 as a new assembly site for selected VSC7427, VSC7422, VSC7421, VSC7420, VSC7429, VSC7425, VSC7423, VSC7426, VSC8512, VSC7424 and VSC7428 device families available in 672L HSBGA (27x27mm) package.

Affected CPNs:

JPZA-02GYZA830_Affected_CPN_09142026.pdf
JPZA-02GYZA830_Affected_CPN_09142026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as a new assembly site for selected VSC7427, VSC7422, VSC7421, VSC7420, VSC7429, VSC7425, VSC7423, VSC7426, VSC8512, VSC7424 and VSC7428 device families available in 672L HSBGA (27x27mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	ASE Inc. (ASEK)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Yes

Wire Material	CuPdAu	CuPdAu	No
Die Attach Material	2100A (PFAS)	2100ANP (PFAS-Free)	Yes
Molding Compound Material	CEL-9750ZHF10AKLE-U	G750SE	Yes
Substrate Core Material	E-679FGB	HL832NXA	Yes
SM Material	AUS308	AUS308	No
Solder Ball Material	SAC305	SAC305	No
Heat spreader Material	C1100	C1100	No
HS Attach Material	CRM-1079B	ME-1070	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity and on-time delivery performance by qualifying ATP7 as a new assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: 12 February 2027

Estimated First Ship Date: 01 October 2026 (date code: 2640)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Due to unforeseen circumstances, that are out of Microchip's control, full qualification will be made available as soon as it is approved which may be after the estimated first ship date so that Microchip can maintain continuity of supply and not disrupt customer orders.

Timetable Summary:

	August 2026					**September 2026**				**October 2026**					**>**	**February 2027**				
Work Week	31	32	33	34	35	36	37	38	39	40	41	42	43	44		06	07	08	09	10

Initial PCN Issue Date		x																	
Qual Report Availability																x			
Final PCN Issue Date								x											
Estimated Implementation Date										x									

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Note 1: This final PCN will be updated to include the Qualification report as soon as it is completed.
Note 2: Please be advised the qualification completion times may be extended because of unforeseen business conditions.

Revision History: August 07, 2026: Issued initial notification.
September 14, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_JPZA-02GYZA830_Qualification_Plan.pdf
PFAS Elimination and Die Attach_Explanation.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

VSC7427XJG-02

VSC7422XJG-02

VSC7421XJG-02

VSC7420XJG-04

VSC7421XJG-04

VSC7422XJG-04

VSC7429XJG-02

VSC7425XJG-02

VSC7423XJG-02

VSC7426XJG-02

VSC8512XJG-03

VSC7424XJG-02

VSC8512XJG-02

VSC7420XJG-02

VSC7428XJG-02

VSC7428XJG-12

VSC7424XJG-12

VSC7427XJG-12

QUALIFICATION PLAN SUMMARY

PCN#: JPZA-02GYZA830

DATE:
August 03, 2026

Qualification of ATP7 as a new assembly site for selected VSC7427, VSC7422, VSC7421, VSC7420, VSC7429, VSC7425, VSC7423, VSC7426, VSC8512, VSC7424 and VSC7428 device families available in 672L HSBGA (27x27mm) package.

Purpose: Qualification of ATP7 as a new assembly site for selected VSC7427, VSC7422, VSC7421, VSC7420, VSC7429, VSC7425, VSC7423, VSC7426, VSC8512, VSC7424 and VSC7428 device families available in 672L HSBGA (27x27mm) package.

CCB No.: 8382

Misc.	Assembly site	ATP7
	MP Code (MPC)	ST402
	Part Number (CPN)	ST402
	MSL information	MSL4 / 250
	Assembly Shipping Media (T/R, Tube/Tray)	Tray
	Base Quantity Multiple (BQM)	40
	Reliability Site	MTAI
Substrate	Core Material	HL832NXA
	Core Thickness	100 um
	L1/L2 Thickness (um)	L1/L4 15 um; L2/L3 72 um
	SM Material	AUS308
	Process	MEBS
	SM Thickness	30 um
	Part Number	101435887
	Drill Size	200 um
	Line/Space Specs	50/50 um
Bond Wire	Material	CuPdAu
Die Attach	Part Number	2100ANP
	Conductive	Yes
MC	Part Number	G750SE
Heat Spreader	Part Number	101435910
	Material	C1100
HS Attach	Part Number	ME-1070
PKG	Package Type	HSBGA
	Pin/Ball Count	672
	PKG width/size	27x27mm
	Ball Pitch/Size	1.0mm / 0.60mm
	Solder Ball Material	SAC305

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5			30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		5			30 bonds from a min. 5 devices.
Solder Ball Shear	JESD22B117A	5	0	3	15		5			10 balls/5 units. Parts should gone Preconditioning
Physical Dimensions	Measure per JESD22 B100	10	0	3	30		5			
High Temperature Storage Life (HTSL)	JESD22-A103. +150°C for 1008 hours Readpoints at 0, 504, and 1008 hours. Electrical test pre and post	45	5	3	150	0	45	MTAI	MTAI	Spare should be properly identified.
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec STD-020E for package type; Electrical test pre and post stress at +25°C. JESD22A113. MSL4 / 250	231	15	3	738	0	15	MTAI	MTAI	Spares should be properly identified. 231 parts from each lot to be used for HAST, uHAST & Temp Cycle test.
THB Alternate to HAST	JESD22-A101 +85°C/85%RH for 1000 hrs	77	5	3	246	0	10			
Unbiased HAST	JESD22-A118. +130°C/85% RH for 96 hours or +110°C/85% RH for 264 hours. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -55°C to +125°C for 1000 cycles or -65°C to +150°C for 500 cycles. Electrical test pre and post stress at room temp. WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	30	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

Eliminating PFAS from Microchip ICs



A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



Microchip

August 2025

Eliminating PFAS from MCHP ICs

- What is PFAS
- Microchip's Environmental Stewardship
- Microchip Products with PFAS
- Time Frame to PFAS-Free Die Attach
- What is Die Attach
- Will clients be required to switch to PFAS free products
- Risk Assessment

What is PFAS: Poly(Per) FluoroAlkyl Substances (PFAS)

Poly(Per) FluoroAlkyl Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
  - PFAS can be in the product itself.
  - PFAS can also be used to manufacture products while not in the product itself

PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

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Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

Achieving "PFAS-Free" status may serve as a competitive advantage for both Microchip and its clients.

Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

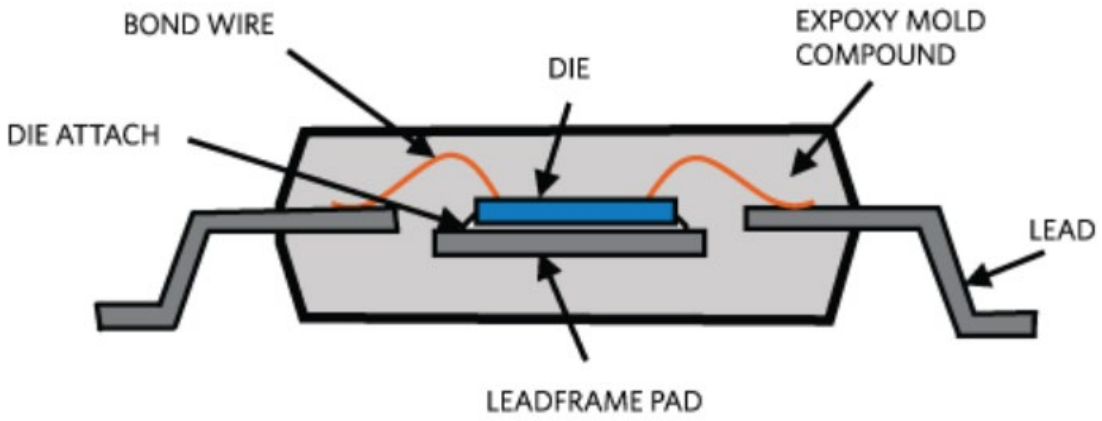
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

What is die attach



A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

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Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.



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